

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chen-Hua Yu	11/23/2011
Chien-Chia Chiu	11/22/2011
Cheng-Chieh Hsieh	11/22/2011
RECEIVING PARTY DATA	
Name:	Taiwan Semiconductor Manufacturing Co., Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13308742
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NAME OF SUBMITTER:	Thomas G. Eschweiler
Total Attachments: 5 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif	

OP \$40.00 13308742

2011-0871

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PARTIES TO THE ASSIGNMENT

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AGREEMENT

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of an invention entitled
"INTERPOSER WAFER BONDING METHOD AND APPARATUS" for which:

a non-provisional application for United States Letters Patent:

was executed on even date preparatory to filing (each inventor should sign this
Assignment on the same day as he/she signs the Declaration and Power of
Attorney); or

was filed on _____ and accorded U.S. Serial No. _____; or

will be filed without this executed PATENT ASSIGNMENT. ASSIGNOR hereby authorizes and requests ASSIGNEE'S legal representatives, the attorneys associated with Customer No. _____, to insert below in this document this APPLICATION's U.S. Serial Number and filing date, when known:

U.S. Serial No. _____,

filed on _____.

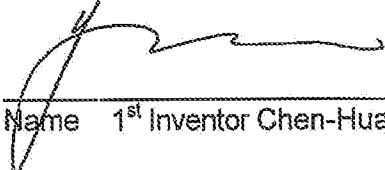
WHEREAS, ASSIGNEE (listed above), a corporation of the Republic of China is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sell, assign and transfer unto ASSIGNEE its successors and assigns, the entire right, title and interest in and to said invention and improvements, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues, re-examinations and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNOR(S) had this assignment, transfer and sale not been made. ASSIGNOR(S) hereby authorize and request the Commissioner of Patents and Trademarks to issue all

letters patent on said invention to ASSIGNEE. ASSIGNOR(S) agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

11/23/11

Date



Name 1st Inventor Chen-Hua Yu

Nov, 22, 2011

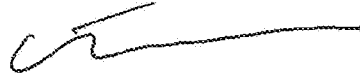
Date



Name 2nd Inventor Chien-Chia Chiu

Nov. 22, 2011

Date



Name 3rd Inventor Cheng-Chieh Hsieh